

MECHANICAL CASE OUTLINE

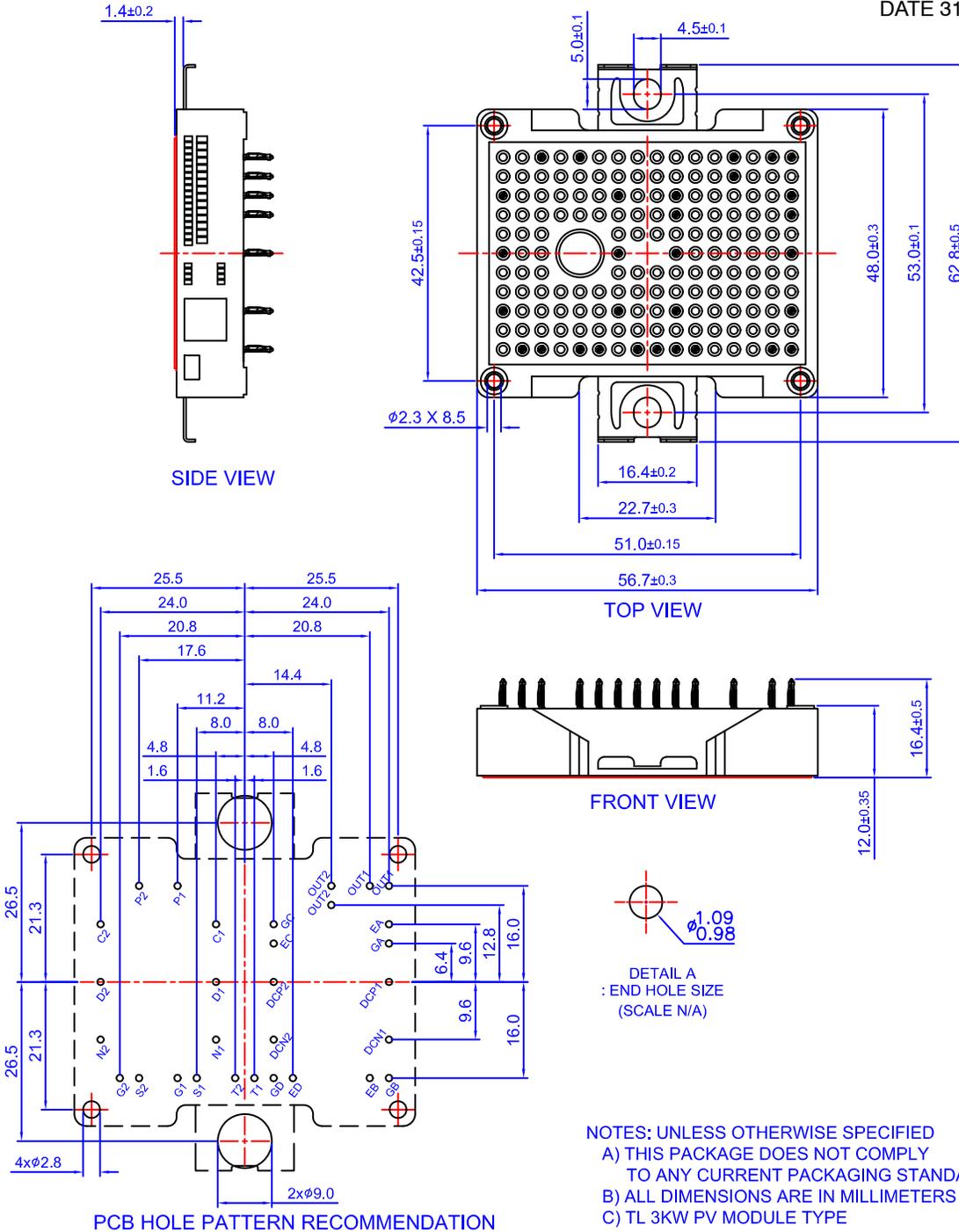
PACKAGE DIMENSIONS

ON Semiconductor®



HF2EA-P30 / 30LD, HPM, F2 PKG, PRESSFIT TERMINAL, TL 3KW PV MODULE CASE MODCU ISSUE O

DATE 31 DEC 2016



- PIN-GRID 3.2mm
- TOLERANCE OF PCB HOLE PATTERN $\varnothing 0.1$

DOCUMENT NUMBER:	98AON13520G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	HF2EA-P30 / 30LD, HPM, F2 PKG, PRESSFIT TERMINAL	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.